

In re Patent Application of:
VINSON ET AL.
Serial No. 10/696,918
Filing Date: October 30, 2003

In the Claims:

Claims 1-9 (CANCELLED)

10. (CURRENTLY AMENDED) An integrated circuit chip module comprising:

a substrate;

~~an integrated at least one integrated~~ circuit die mounted directly on the substrate and having die pads and an exposed surface opposite from the substrate;

a plurality of substrate bonding pads positioned directly on the substrate adjacent the integrated circuit die;

a plurality of decoupling capacitor assemblies mounted in series directly on the integrated circuit die, each decoupling capacitor assembly comprising

a capacitor carrier secured onto the exposed surface of the integrated circuit die,

a thin film metallization layer formed directly on said capacitor carrier;

a conductive adhesive layer applied directly onto
said thin film metallization layer;

a decoupling capacitor secured directly onto said
thin film metallization layer by said conductive adhesive
layer;

~~a conductive adhesive layer positioned between said~~
~~decoupling capacitor and thin film metallization layer and~~
~~securing said decoupling capacitor on said thin film~~
~~metallization layer;~~

In re Patent Application of:
VINSON ET AL.
Serial No. 10/696,918
Filing Date: October 30, 2003

a wire bond extending from the thin film metallization layer to a logic pin of the integrated circuit die; and

a wire bond extending from a logic pin to a substrate bonding pad.

11. (CANCELLED)

12. (CANCELLED)

13. (CANCELLED)

14. (CANCELLED)

15. (ORIGINAL) An integrated circuit chip module according to Claim 10, wherein said capacitor carrier is formed from an aluminum nitride substrate.

16. (ORIGINAL) An integrated circuit chip module according to Claim 15, wherein said aluminum nitride substrate ranges in thickness from about 5 mil to about 50 mil.

17. (CANCELLED)

18. (ORIGINAL) An integrated circuit chip module according to Claim 10, and including a bonding pad on said thin film metallization layer for securing a wire bond.

Claims 19-38 (CANCELLED)